

1 **WHAT IS CLAIMED IS:**

2 1. A method for making an optical interference type display panel, the
3 method comprising the steps of:
4 providing a substrate (10);
5 sequentially forming a plurality of first conductive optical film stacks (20), a
6 supporting layer (11), a spacing layer (12) and a plurality of second conductive
7 optical film stacks (13) on the substrate (10); and
8 forming a plurality of connecting pads (201)(202) near edges of the
9 substrate (10), wherein the plurality of connecting pads (201)(202) is made of a
10 transparent conductive layer (21) of the first conductive optical film stack (20).

11 2. The method as claimed in claim 1, the method further comprising the
12 steps of:

13 forming the plurality of separated first conductive optical film stacks (20)
14 on the substrate (10);

15 defining patterns of connecting pads, wherein portions of these first
16 conductive optical film stacks (20) are further patterned to form the plurality of
17 connecting pads (201)(202);

18 forming the supporting layer (11) on the substrate (10), wherein the
19 supporting layer (11) is formed between two separated first conductive optical
20 film stacks (20);

21 forming the spacing layer (12), wherein the spacing layer (12) is formed
22 above each separated first conductive optical film stack (20) and is further
23 flattened;

24 forming the plurality of second conductive optical film stacks (13), wherein

1 these second conductive optical film stacks (13) are coated on the spacing layer
2 (12) and the supporting layer (11), and the second conductive optical film stacks
3 (13) are electrically connected to a portion of the plurality of the connecting pads
4 (202); and

5 removing the spacing layer (12), wherein once the spacing layer (12) has
6 been removed from the substrate (10), a gap is defined between the first and the
7 second conductive optical film stacks (20)(13).

8 3. The method as claimed in claim 1, wherein the first conductive optical
9 film stack (20) is formed by the step of:

10 sequentially forming a transparent conductive layer (21a), an absorption
11 layer (22a) and a dielectric layer (24a) on the substrate (10).

12 4. The method as claimed in claim 2, wherein the first conductive optical
13 film stack (20) is formed by the step of:

14 sequentially forming a transparent conductive layer (21a), an absorption
15 layer (22a) and a dielectric layer (24a) on the substrate (10).

16 5. The method as claimed in claim 1, wherein the first conductive optical
17 film stack (20) is formed by the step of:

18 sequentially forming a first dielectric layer (23b), a transparent conductive
19 layer (21b), an absorption layer (22b) and a second dielectric layer (24b) on the
20 substrate (10).

21 6. The method as claimed in claim 2, wherein the first conductive optical
22 film stack (20) is formed by the step of:

23 sequentially forming a first dielectric layer (23b), a transparent conductive
24 layer (21b), an absorption layer (22b) and a second dielectric layer (24b) on the

1 substrate (10).

2 7. The method as claimed in claim 1, wherein the first conductive optical
3 film stack (20) is formed by the step of:

4 sequentially forming a transparent conductive layer (21c), a first dielectric
5 layer (23c), an absorption layer (22c) and a second dielectric layer (24c) on the
6 substrate (10).

7 8. The method as claimed in claim 2, wherein the first conductive optical
8 film stack (20) is formed by the step of:

9 sequentially forming a transparent conductive layer (21c), a first dielectric
10 layer (23c), an absorption layer (22c) and a second dielectric layer (24c) on the
11 substrate (10).

12 9. The method as claimed in claim 1, wherein the first conductive optical
13 film stack (20) is formed by the step of:

14 sequentially forming a first dielectric layer (23d), an absorption layer (22d)
15 a transparent conductive layer (21d) and a second dielectric layer (24d) on the
16 substrate (10).

17 10. The method as claimed in claim 2, wherein the first conductive optical
18 film stack (20) is formed by the step of:

19 sequentially forming a first dielectric layer (23d), an absorption layer (22d)
20 a transparent conductive layer (21d) and a second dielectric layer (24d) on the
21 substrate (10).

22 11. An optical interference display panel comprising:

23 a substrate on which a plurality of first conductive optical film stacks (20), a
24 supporting layer (11) and a plurality of second conductive optical film stacks (13)

1 are formed; and

2 a plurality of connecting pads (201)(202) formed near edges of the substrate
3 (10), wherein the plurality of connecting pads (201)(202) are made of a
4 transparent conductive layer (21) of the first conductive optical film stack (20).

5 12. The display panel as claimed in claim 11, the first conductive optical
6 film stack (20) comprising a transparent conductive layer (21a), an absorption
7 layer (22a) and a dielectric layer (24a) on the substrate (10), which are
8 sequentially formed on the substrate (10).

9 13. The display panel as claimed in claim 11, the first conductive optical
10 film stack (20) comprising a first dielectric layer (23b), a transparent conductive
11 layer (21b), an absorption layer (22b) and a second dielectric layer (24b), which
12 are sequentially formed on the substrate (10).

13 14. The display panel as claimed in claim 11, the first conductive optical
14 film stack (20) comprising a transparent conductive layer (21c), a first dielectric
15 layer (23c), an absorption layer (22c) and a second dielectric layer (24c), which
16 are sequentially formed on the substrate (10).

17 15. The display panel as claimed in claim 11, the first conductive optical
18 film stack (20) comprising a first dielectric layer (23d), an absorption layer (22d)
19 a transparent conductive layer (21d) and a second dielectric layer (24d), which
20 are sequentially formed on the substrate (10).